



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10B683KB8SFNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 68nF, 50V, ±10%, X7R, 0603

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>B</u> <u>683</u> <u>K</u> <u>B</u> <u>8</u> <u>S</u> <u>F</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Ser	ies Samsung	Samsung Multi-layer Ceramic Capacitor						
② Size	e 0603 (i	inch code) L	: 1.6	± 0.1	mm	W:	0.8 ± 0.1	mm
3 Die	lectric X7R		8	Inner ele	ctrode	N	i	
4 Cap	pacitance 68 n	nF		Terminat	tion	M	letal Epoxy	
⑤ Cap	pacitance ±10 %	%		Plating		S	n 100%	(Pb Free)
tole	erance		9	Product		Р	roduct for P	OWER application
6 Rat	ed Voltage 50 V	/	10	Special		R	eserved for	future use
7 Thi	ckness 0.8 ±	± 0.1 mm	11)	Packagir	ng	С	ardboard Ty	rpe,7"reel(4,000ea)

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition				
Capacitance	Within specified tolerance	1klb±10% 1.0±0.2Vrms				
Tan δ (DF)	0.025 max.					
Insulation	More than 500Mohm⋅ <i>μ</i> Γ	Rated Voltage 60~120 sec.				
Resistance						
Appearance	No abnormal exterior appearance	Visual inspection				
Withstanding	No dielectric breakdown or	250% of the rated voltage				
Voltage	mechanical breakdown					
Temperature	X7R					
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±15%)					
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.				
of Termination	terminal electrode					
Bending Strength	Capacitance change: within ±12.5%	Bending to the limit (1mm)				
		with 1.0mm/sec.				
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder				
	is to be soldered newly	245±5°C, 3±0.3sec.				
		(preheating : 80~120 ℃ for 10~30sec.)				
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.				
Soldering heat	Tan δ, IR : initial spec.					

	Performance	Test condition				
Vibration Test	Capacitance change: within ±5%	Amplitude : 1.5mm				
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)				
		2hours × 3 direction (x, y, z)				
Moisture	Capacitance change: within ±12.5%	With rated voltage				
Resistance	Tan δ : 0.05 max	40±2℃, 90~95%RH, 500+12/-0 hours.				
	IR : More than 25MΩ·μF					
High Temperature	Capacitance change : within ±12.5%	With 200% of the rated voltage				
Resistance	Tan δ : 0.05 max	Max. operating temperature				
	IR : More than 50MΩ·μF					
		1000+48/-0 hours.				
Temperature	Capacitance change: within ±7.5%	1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C				
		→ Max. operating temperature → 25°C				
		5 cycles test.				

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}\!\text{C}$, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.